502616818 12/31/2013

PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT2663413

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
YONGGEN HE	12/13/2013

RECEIVING PARTY DATA

Name:	SEMICONDUCTOR MANUFACTURING INTERNATIONAL (BEIJING) CORPORATION	
Street Address:	NO. 18, WEN CHANG RD., ECONOMIC-TECHNOLOGICAL, DEVELOPMENT AREADAXING DISTRICT,	
City:	BEIJING	
State/Country:	CHINA	
Postal Code:	100716	

Name:	SEMICONDUCTOR MANUFACTURING INTERNATIONAL (SHANGHAI) CORPORATION,	
Street Address:	: 18 ZHANGJIANG ROAD, PUDONG NEW AREA,	
City:	SHANGHAI	
State/Country:	CHINA	
Postal Code:	201203	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	14144696

CORRESPONDENCE DATA

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<u>PATENT</u>
REEL: 031861 FRAME: 0570

OP \$40,00 14144696

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ATTORNEY DOCKET NUMBER:	00158.0152.00US
NAME OF SUBMITTER:	GRACE GAO
Signature:	/Grace Gao/
Date:	12/31/2013
Total Attachments: 2 source=Assignment1580152#page1.tif source=Assignment1580152#page2.tif	

PATENT REEL: 031861 FRAME: 0571 SMIC 2013-00279-SH-US Anova Law Group, PLLC 00158.0152.00US US Rights Page 1

ASSIGNMENT

WHEREAS I/We, the below named inventor(s) (hereinafter referred to as Assignor(s)) have made an invention entitled:
TRANSISTORS AND FABRICATION METHODS THEREOF
for which I/We executed an application for United States Letters Patent concurrently herewith or filed an application for United States Letters Patent on(Application No); and
WHEREAS, Semiconductor Manufacturing International (Beijing) Corporation, a corporation of P. R. China whose post office address is No. 18, Wen Chang Rd., Economic-Technological, Development Area, Daxing District, Beijing, China, 100716, and Semiconductor Manufacturing International (Shanghai) Corporation, a corporation of P. R. China whose post office address is 18 Zhangjiang Road, Pudong New Area, Shanghai, China 201203 (hereinafter referred to as Assignee), is desirous of securing the entire right, title, and interest in and to this invention in all countries throughout the world, and in and to the application for United States Letters Patent on this invention and the Letters Patent to be issued upon this application;
NOW THEREFORE, be it known that, for good and valuable consideration the receipt of which from Assignee is hereby acknowledged, I/We, as Assignor(s), have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto the Assignee, its lawful successors and assigns, my/our entire right, title, and interest in and to this invention, provisional Application No
AND, I/WE HEREBY covenant that I/We have the full right to convey the interest assigned by this Assignment, and I/We have not executed and will not execute any agreement in conflict with this Assignment;
AND, I/WE HEREBY further covenant and agree that I/We will, without further consideration, communicate with Assignee, its successors and assigns, any facts known to me/us respecting this invention, and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver any and all papers that may be necessary or desirable to perfect the title to this invention in said Assignee, its successors or assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid Assignee, its successors and assigns, to obtain and enforce proper patent protection for this invention in the United States and any foreign country, it being understood that any expense incident to the execution of such papers shall be borne by the Assignee, its successors and assigns.
AND, I/WE HEREBY authorize and request the attorneys I/we have empowered in the Declaration and Power of Attorney in this application, to insert here in parentheses (Application Nofiled) the filing date and application number of said application when known.

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IN TESTIMONY WHEREOF, I/We have hereunto set our hands.

Inventor:

Name:

YONGGEN HE

Address:

18 Zhangjiang Road, Pudong New Area

Shanghai, China 201203

Signature:

Yongger

He

Date:

2013.12.13